

ABSTRACT

A ball grid array mounted circuit includes a stress relief substrate having spaced conductive vias extending between its surfaces and connection pads at the surfaces. Solder connections formed from solder balls connect between pads at the top surface and connection pads at an electronic component. Solder connections formed from solder balls connect between pads at the bottom surface and connection pads at a printed circuit board (PCB). The solder connections absorb at least a portion of the stress due to differences between the thermal coefficient of expansion of the electronic component and the PCB.